



**Applications of Lead, Mercury, Cadmium, Chromium VI, Polybrominated Biphenyls (PBB) and Polybrominated Diphenyl Ethers (PBDE) which are exempted from the requirements of Article 4(1) of Directive 2002/95/EC.**

1. Mercury in compact fluorescent lamps not exceeding 5mg per lamp.
2. Mercury in straight fluorescent lamps for general purposes not exceeding:

Halophosphate	10mg
Triphosphate with normal lifetime	5mg
Triphosphate with long lifetime	8mg.
3. Mercury in straight fluorescent lamps for special purposes.
4. Mercury in other lamps not specifically mentioned in this Annex
5. Lead in glass of cathode ray tubes, electronic components and fluorescent tubes.
6. Lead as an alloying element in steel containing up to 0.35% lead by weight, aluminium containing up to 0.4% lead by weight and as a copper alloy containing up to 4% lead by weight.
7. Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead),  
Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signalling, transmission as well as network management for telecommunications,  
Lead in electronic ceramic parts (e.g. piezoelectronic devices).
8. Cadmium and its compounds in electrical contacts and cadmium plating except for applications banned under Directive 91/338/EEC amending Directive 76/769/EEC relating to restrictions on the marketing and use of certain dangerous substances and preparations.
9. Hexavalent chromium as an anti-corrosion of the carbon steel cooling system in absorption refrigerators
10. DecaBDE in polymeric applications  
Lead in lead-bronze bearing shells and bushes.
11. Lead used in compliant pin connector systems.
12. Lead as a coating material for the thermal conduction module c-ring.
13. Lead and cadmium in optical and filter glass.
14. Lead in solders consisting of more than two elements for the connection between the pins and the package of microprocessors with a lead contact of more than 80% and less than 85% by weight.
15. Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages.
16. Lead in linear incandescent lamps with silicate coated tubes.
17. Lead halide as radiant agent in High Intensity Discharge (HID) lamps used for professional reprography applications.

***Please Note: The exemption status of each of the above applications must be considered as temporary. Additionally, applications can be added to the list in accordance with the E.U. Commission's decisions. While this list is regularly updated, the Environmental Protection Agency accepts no liability for consequences of any party acting or refraining from acting on the information provided. In order to obtain information on the current exemption status of any of the applications listed, it is strongly advised to contact the Environmental Protection Agency on 00353 53 60600.***



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18. Lead as activator in the fluorescent powder (1% lead by weight or less) of discharge lamps when used as sun tanning lamps containing phosphors such as BSP (BaSi<sub>2</sub>O<sub>5</sub>:Pb) as well as when used as speciality lamps for diazo-printing reprography, lithography, insect traps, photochemical and curing processes containing phosphors such as SMS ((Sr,Ba)<sub>2</sub>MgSi<sub>2</sub>O<sub>7</sub>:Pb).
19. Lead with PbBiSn-Hg and PbInSn-Hg in specific compositions as main amalgam and with PbSn-Hg as auxiliary amalgam in very compact Energy Saving lamps (ESL).
20. Lead oxide in glass used for bonding front and rear substrates of flat fluorescent lamps used for Liquid Crystal displays (LCD).
21. Lead and cadmium in printing inks for the application of enamels on borosilicate glass.
22. Lead as impurity in RIG (rare earth iron garnet) Faraday rotators used for fibre optic communications systems.
23. Lead in finishes of fine pitch components other than connectors with a pitch of 0.65mm or less with NiFe lead frames and lead in finishes of fine pitch components other than connectors with a pitch of 0.65mm or less with copper lead frames.
24. Lead in solders for the soldering of machined through hole discoidal and planar array ceramic multilayer capacitors.
25. Lead oxide in plasma display panels (PDP) and surface conduction electron emitter displays (SED) used in structural elements; notably in the front and rear glass dielectric layer, the bus electrode, the black stripe, the address electrode, the barrier ribs, the seal frit and frit ring as well as in print pastes.
26. Lead oxide in the glass envelope of Black Light Blue (BLB) lamps.
27. Lead alloys as solder for transducers used in high-powered (designated to operate for several hours at acoustic power levels of 125dB SPL and above) loudspeakers.
28. Hexavalent chromium in corrosion preventive coatings of unpainted metal sheetings and fasteners used for corrosion protection and Electromagnetic Interference Shielding in equipment falling under category three of Directive 2002/96/EC (IT and telecommunications equipment). Exemption granted until 1 July 2007.
29. Lead bound in crystal glass as defined in Annex I (Categories 1, 2, 3 and 4) of Council Directive 69/493/EEC\*.

*\*OJ L 326, 29.12.1969, p. 36. Directive as last amended by 2003 Act of Accession.*

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